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AN - 1991-159506 [22]

AP - JP19890232236 19890907

CPY - ORIE-N

DC - L03 M13

DR - 1149-U 1175-U 1512-U 1514-U

FS - CPI

IC - C23C18/18

MC - M13-B M14-A02 M14-A03

PA - (ORIE-N) ORIENT TOKEI KK

PN - JP3094072 A 19910418 DW199122 000pp

PR - JP19890232236 19890907

XA - C1991-068947

XIC - C23C-018/18

AB - J03094072 Process comprises metal surface by substd. by etching and electroless plating. The first etching process occurs by applying etchant of mixed soln. including NaOH, KOH, KCN, NaCN with 10-80 g/L, at 5-35 deg. C. The second process is metal surface substd. by electroless plating using soln. of PdCl<sub>2</sub>, Pd (NO<sub>3</sub>)<sub>2</sub>, PdSO<sub>4</sub>, Pd (COOH)<sub>2</sub> or its salt concn, 0.1-1.0 g/L and pH 10-12, applied at 5-35 deg. C.

- USE/ADVANTAGE - For plating onto thin metal foil or film of electronic devices. Useful to Al foil pattern. (6pp Dwg.No.0/1)

IW - PROCESS METAL SURFACE SUBSTITUTE ETCH STEP HYDROXIDE CYANIDE SOLUTION  
SODIUM POTASSIUM PALLADIUM SOLUTION ELECTROLESS PLATE

IKW - PROCESS METAL SURFACE SUBSTITUTE ETCH STEP HYDROXIDE CYANIDE SOLUTION  
SODIUM POTASSIUM PALLADIUM SOLUTION ELECTROLESS PLATE

NC - 001

OPD - 1989-09-07

ORD - 1991-04-18

PAW - (ORIE-N) ORIENT TOKEI KK

TI - Process for metal surface substitution - has etching step using hydroxide and cyanide soln. of sodium and potassium, and using palladium soln. for electroless plating